**Title**

**Size**

**Document Number**

**Rev**

**Date**: Friday, March 31, 2017

**Sheet**

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**R4 & R179 share a pad.**

**R6 & R151 share a pad.**

**R9 & R162 share a pad.**

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**Only the P and M's need to match.**

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**Texas Instruments**

**ANALOG IN**

**TIDA-01442**

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**Components Diagram**

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**Notes**

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**Reference**

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**Revision**

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**Bill of Materials**

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**Footer**

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Place near Vc pin of Y1 R20 and C31 form voltage divider set the center frequency voltage for PLL2 reference

Place close to LMK

MATCHED LENGTH

Place close to LMK

MATCHED LENGTH

Y1 CMOS version OUTPUT on PIN 4
Make sure this line does not hold LMK high before LMK can be programmed for SDO.
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